

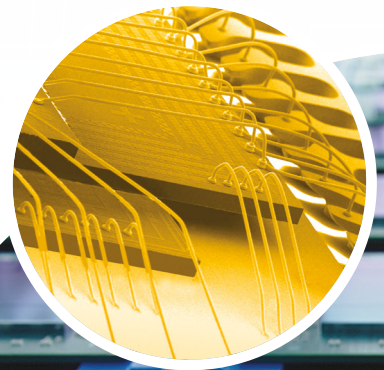
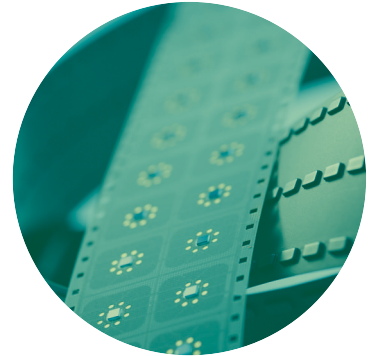
MATERIALS DIVISION

For materials and machine consumable products used in the assembly of photonic, semiconductor, high-frequency and microelectronic devices.

Products & services include: metalised thin film substrates, thick film pastes, glazes and specialty powders, precision micro-stampings, solder spheres & preforms, die attach adhesives, bonding wires & ribbons, thermal dissipation materials, stamped heatsinks, hermetic glass & ceramic HTCC packages, package lids and glob-tops, welding electrodes & thermodes, plus bonding wedges, capillaries, die collets, pickup tools & dicing blades etc.

Supplying the UK, Ireland and Northern European regions, Inseto aims to exceed customer expectations and is committed to a policy of continuous improvement throughout the company.

Inseto's other product divisions comprise semiconductor Wafers and Equipment for device fabrication, assembly and test, plus Adhesives for electronic, automotive and industrial applications.



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**Tel: +44 (0)1264 334505 Email: enquiries@inseto.co.uk
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Inseto (UK) Limited,
Unit 25 Focus Way, Andover SP10 5NY
United Kingdom



MATERIALS DIVISION

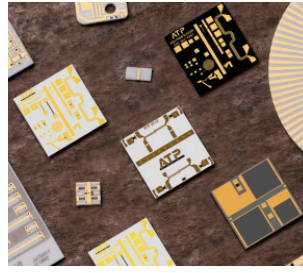
HUBBED DICING BLADES



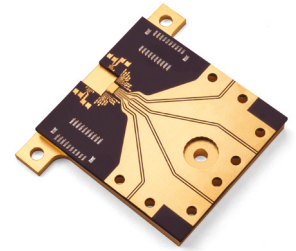
HUBLESS ANNULAR DICING BLADES



METALISED THIN FILM



HIGH FREQUENCY SUBSTRATES



THICK FILM MATERIALS



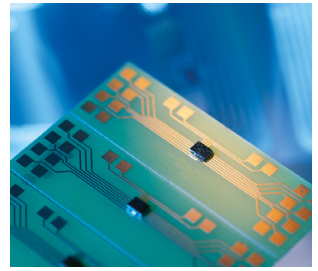
METAL MICRO-STAMPINGS



SOLDER PREFORMS



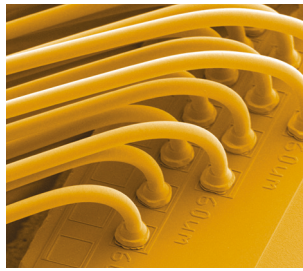
DIE ATTACH ADHESIVES



DIE ATTACH TOOLING



GOLD BONDING WIRE & RIBBON



BONDING CAPILLARIES



ALUMINIUM BONDING WIRE & RIBBON



BONDING WEDGES



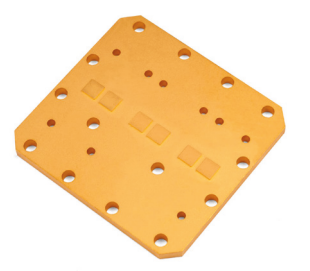
WELDING ELECTRODES & HOT BAR THERMODES



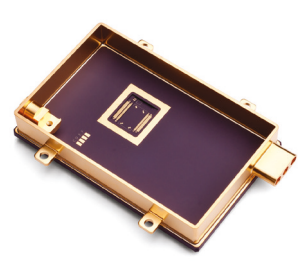
STAMPED HEATSINKS



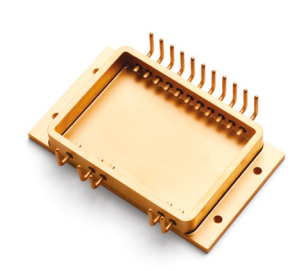
THERMAL MANAGEMENT



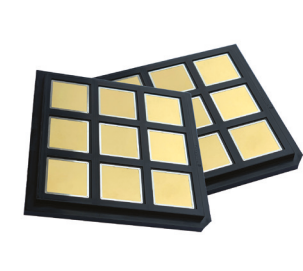
CERAMIC PACKAGES



HERMETIC PACKAGES



PACKAGE COVER LIDS



GLOB TOP ENCAPSULANTS

